

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM379666

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|---|---|-----------------------|-----------------------|
| SUBMISSION TYPE: | NEW ASSIGNMENT | | |
| NATURE OF CONVEYANCE: | Amended and Restated Intellectual Property Security Agreement | | |
| CONVEYING PARTY DATA | | | |
| Name | Formerly | Execution Date | Entity Type |
| ENDWAVE CORPORATION | | 04/05/2016 | Corporation: DELAWARE |
| RECEIVING PARTY DATA | | | |
| Name: | Silicon Valley Bank | | |
| Street Address: | 2400 Hanover Street | | |
| City: | Palo Alto | | |
| State/Country: | CALIFORNIA | | |
| Postal Code: | 95134 | | |
| Entity Type: | Corporation: CALIFORNIA | | |
| PROPERTY NUMBERS Total: 1 | | | |
| Property Type | Number | Word Mark | |
| Registration Number: | 2496013 | ENDWAVE | |
| CORRESPONDENCE DATA | | | |
| Fax Number: | 8004947512 | | |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | | | |
| Phone: | 202-370-4750 | | |
| Email: | ipteam@nationalcorp.com | | |
| Correspondent Name: | Darlena Bari Stark | | |
| Address Line 1: | 1025 Vermont Ave NW, Suite 1130 | | |
| Address Line 2: | National Corporate Research, Ltd. | | |
| Address Line 4: | Washington, D.C. 20005 | | |
| ATTORNEY DOCKET NUMBER: | F162326 | | |
| NAME OF SUBMITTER: | James Won | | |
| SIGNATURE: | /James Won/ | | |
| DATE SIGNED: | 04/06/2016 | | |
| Total Attachments: 10 | | | |
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AMENDED AND RESTATED INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Amended and Restated Intellectual Property Security Agreement (this "Agreement") is entered into as of April 5, 2016 by and between **SILICON VALLEY BANK**, a California corporation, with a loan production office located at 2400 Hanover Street, Palo Alto, California 95134 ("Bank") and **ENDWAVE CORPORATION**, a Delaware corporation, with its principal place of business located at 130 Baytech Drive, San Jose, CA 95134 ("Grantor").

RECITALS

A. Bank has agreed to make certain advances of money and to extend certain financial accommodations to Grantor, **GIGOPTIX, INC.**, a Delaware corporation, **CHIPX, INCORPORATED**, a Delaware corporation, and **MAGNUM SEMICONDUCTOR, INC.**, a Delaware corporation (jointly and severally, individually and collectively "Borrower") (the "Loans") in the amounts and manner set forth in that certain Third Amended and Restated Loan and Security Agreement by and between Bank and Grantor dated as of the date hereof (as the same may be amended, modified or supplemented from time to time, the "Loan Agreement"; capitalized terms used herein are used as defined in the Loan Agreement). Bank is willing to make the Loans to Borrower, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in its Copyrights, Trademarks, Patents, and Mask Works (as each term is described below) to secure the obligations of Borrower to Bank.

B. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor's right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of Borrower's obligations to Bank, Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

1. Grant of Security Interest. To secure Borrower's obligations to Bank, Grantor grants and pledges to Bank a security interest in all of Grantor's right, title and interest in, to and under its intellectual property (all of which shall collectively be called the "Intellectual Property Collateral"), including, without limitation, the following:

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work of authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, now or hereafter existing, created, acquired or held, including without limitation those set forth on Exhibit A attached hereto (collectively, the "Copyrights");

(b) Any and all trade secrets, and any and all intellectual property rights in computer software and computer software products now or hereafter existing, created, acquired or held;

(c) Any and all design rights that may be available to Grantor now or hereafter existing, created, acquired or held;

(d) All patents, patent applications and like protections including, without limitation, improvements, divisions, continuations, renewals, reissues, extensions and continuations-in-part of the same, including without limitation the patents and patent applications set forth on Exhibit B attached hereto (collectively, the "Patents");

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation those set forth on Exhibit C attached hereto (collectively, the "Trademarks");

(f) All mask works or similar rights available for the protection of semiconductor chips, now owned or hereafter acquired, including, without limitation those set forth on Exhibit D attached hereto (collectively, the "Mask Works");

(g) Any and all claims for damages by way of past, present and future infringements of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(h) All licenses or other rights to use any of the Copyrights, Patents, Trademarks, or Mask Works and all license fees and royalties arising from such use to the extent permitted by such license or rights;

(i) All amendments, extensions, renewals and extensions of any of the Copyrights, Trademarks, Patents, or Mask Works; and

(j) All proceeds and products of the foregoing, including without limitation all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

2. Recordation. Grantor authorizes the Commissioner for Patents, the Commissioner for Trademarks and the Register of Copyrights and any other government officials to record and register this Agreement upon request by Bank.

3. Loan Documents. This Agreement has been entered into pursuant to and in conjunction with the Loan Agreement, which is hereby incorporated by reference. The provisions of the Loan Agreement shall supersede and control over any conflicting or inconsistent provision herein. The rights and remedies of Bank with respect to the Intellectual Property Collateral are as provided by the Loan Agreement and related documents, and nothing in this Agreement shall be deemed to limit such rights and remedies.

4. Execution in Counterparts. This Agreement may be executed in counterparts (and by different parties hereto in different counterparts), each of which shall constitute an original, but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart of a signature page to this Agreement by facsimile or in electronic (i.e., "pdf" or "tif" format) shall be effective as delivery of a manually executed counterpart of this Agreement.

5. Successors and Assigns. This Agreement will be binding on and shall inure to the benefit of the parties hereto and their respective successors and assigns.

6. Governing Law. This Agreement and any claim, controversy, dispute or cause of action (whether in contract or tort or otherwise) based upon, arising out of or relating to this Agreement and the transactions contemplated hereby and thereby shall be governed by, and construed in accordance with, the

laws of the United States and the State of California, without giving effect to any choice or conflict of law provision or rule (whether of the State of California or any other jurisdiction).

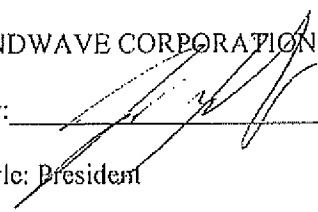
7. Amended and Restated Agreement. This Agreement amends and restates, and replaces, that certain Intellectual Property Security Agreement dated as of December 9, 2011, between Grantor and Bank, as amended.

[Signature page follows.]

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

ENDWAVE CORPORATION

By:  _____

Title: President

BANK:

SILICON VALLEY BANK

By: _____

Title: _____

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:


ENDWAVE CORPORATION

By: _____

Title: _____

BANK:

SILICON VALLEY BANK

By:  _____

Title: Vice president

SCHEDULE A

Endwave Corp. - Copyrights

None.

SCHEDULE B

Endwave Corp. - U.S. Patents

| PATENT NO. | ISSUE DATE | TITLE |
|------------|------------|--|
| 6,194,981 | 2001-02-27 | Slot line band reject filter |
| 6,600,384 | 2003-07-29 | Impedance-compensating circuit |
| 6,640,423 | 2003-11-04 | Apparatus and method for the placement and bonding of a die on a substrate |
| 7,006,794 | 2006-02-28 | Wireless point to multi-point communication apparatus and method |
| 7,109,583 | 2006-09-19 | Mounting with auxiliary bumps |
| 7,119,633 | 2006-10-10 | Compensated interdigitated coupler |
| 7,145,414 | 2006-12-05 | Transmission line orientation transition |
| 7,276,988 | 2007-10-02 | Multi-substrate microstrip to waveguide transition |
| 7,348,666 | 2008-03-25 | Chip-to-chip trench circuit structure |
| 7,411,279 | 2008-08-12 | Component interconnect with substrate shielding |
| 7,588,966 | 2009-09-15 | Chip mounting with flowable layer |
| 7,710,219 | 2010-05-04 | Merged-filter multiplexer |
| 7,813,145 | 2010-10-12 | Circuit structure with multifunction circuit cover |
| D453,152 | 2002-01-29 | Shaped reflector surface of a microwave antenna |
| D453,925 | 2002-02-26 | Shaped reflector surface of microwave antenna |
| D453,927 | 2002-02-26 | Shaped reflector surface of a microwave antenna |
| 4,965,539 | 1990-10-23 | Microwave notch filter using pin diode shunted YIG resonators |
| 4,965,967 | 1990-10-30 | Apparatus for low stress polishing of spherical objects |
| 5,491,449 | 1996-02-13 | Dual-sided push-pull amplifier |
| 5,698,469 | 1997-12-16 | Method of making a hybrid circuit with a chip having active devices with extra-chip interconnections |
| 5,528,203 | 1996-06-18 | Coplanar waveguide-mounted flip chip |
| 5,563,558 | 1996-10-08 | Reentrant power coupler |
| 5,771,449 | 1998-06-23 | Sectorized multi-function communication system |
| 5,623,231 | 1997-04-22 | Push-pull power amplifier |
| 5,610,563 | 1997-03-11 | Slot line to CPW circuit structure |
| 5,789,801 | 1998-08-04 | Varactor with electrostatic barrier |
| 5,668,512 | 1997-09-16 | Coplanar waveguide-mounted flip chip having coupled ground conductors |
| 6,023,209 | 200-02-08 | Coplanar microwave circuit having suppression of undesired modes |
| 5,832,376 | 1998-11-03 | Coplanar mixer assembly |
| 5,942,804 | 1999-08-24 | Circuit structure having a matrix of active devices |
| 5,770,987 | 1998-06-23 | Coplanar waveguide strip band pass filter |
| 5,821,815 | 1998-10-13 | Miniature active conversion between slotline and coplanar waveguide |
| 5,978,666 | 1999-11-02 | Slotline-mounted flip chip structures |
| 5,983,089 | 1999-11-09 | Slotline-mounted flip chip |
| 5,760,650 | 1998-06-02 | Coplanar waveguide amplifier |
| 5,821,827 | 1998-10-13 | Coplanar oscillator circuit structures |
| RE35869 | 1998-08-11 | Miniature active conversion between microstrip and coplanar wave guide |
| 5,942,957 | 1998-08-24 | Flip-mounted impedance |
| 6,002,305 | 1999-12-14 | Transition between circuit transmission line and microwave waveguide |
| 6,023,206 | 2000-02-08 | Slot line band pass filter |
| 6,052,582 | 2000-04-18 | Sectorized multi-function communication system |
| 6,064,253 | 2000-05-16 | Multiple stage self-biasing RF transistor circuit |
| 6,094,114 | 2000-07-25 | Slotline-to-slotline mounted flip chip |
| 6,194,981 | 2001-02-27 | Slot line band reject filter |
| 6,034,580 | 2000-03-07 | Coplanar waveguide filter |

| PATENT NO. | ISSUE DATE | TITLE |
|------------|------------|--|
| 6,265,937 | 2001-07-24 | Push-pull amplifier with dual coplanar transmission line |
| 6,640,423 | 2003-11-04 | Apparatus and method for the placement and bonding of a die on a substrate |
| 7,006,794 | 2006-02-28 | Wireless point to multi-point communication apparatus and method |
| 6,600,384 | 2003-07-29 | Impedance-compensating circuit |
| 7,109,583 | 2006-09-19 | Mounting with auxiliary bumps |

Endwave Corp. - U.S. Patent Applications

| APPLICATION NO. | FILING DATE | TITLE |
|-----------------|-------------|---|
| 09/911,183 | 2001-07-23 | Tunable resonator and method of tuning the same |
| 09/946,972 | 2001-09-04 | Waveguide mixer/coupler |
| 10/010,527 | 2000-03-07 | Filter cartridge comprises ring-shaped filter member with base and outer support ring |
| 10/613,882 | 2003-07-02 | N-way signal divider |
| 10/882,886 | 2004-06-30 | Electromagnetic shield assembly |
| 11/777,096 | 2007-07-12 | Compensated attenuator |
| 12/038,546 | 2008-02-27 | Coaxial-to-microstrip transitions and manufacturing methods |
| 12/391,144 | 2009-02-23 | Distributed amplifier with negative feedback |
| 11/692,129 | 2007-03-27 | Electromagnetic shield assembly |

SCHEDULE C

Endwave Corp. - U.S. Trademarks

| REGISTRATION NO. | REGISTRATION DATE | TRADEMARK |
|-----------------------------|------------------------------|------------------|
| 2496013 | 2001-10-09 | ENDWAVE |

EXHIBIT D

Mask Works

Description

Registration/
Application
Number

Registration/
Application
Date

1959607.1